

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
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JUN AMANO	03/20/2019
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16359125
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DATE SIGNED:	03/20/2019
Total Attachments: 1	
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ASSIGNMENT

WHEREAS I, the below named inventor (hereinafter referred to as Assignor(s)), have made an invention entitled:

FABRICATION PROCESS FOR FLIP CHIP BUMP BONDS USING NANO-LEDs AND CONDUCTIVE RESIN

for which I executed an application for United States Letters Patent concurrently herewith; and

WHEREAS, **KONICA MINOLTA LABORATORY U.S.A., INC.**, a corporation of California whose post office address is 2855 Campus Drive, Suite 100, San Mateo, California 94403, U.S.A. (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I, as Assignor, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my entire right, title, and interest in and to this invention, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, as well as all rights to claim priority on the basis of this application, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment and the Proprietary Rights and Confidentiality Agreement;

AND, I HEREBY covenant that I have the full right to convey the interest assigned by this Assignment, and I have not executed and will not execute any agreement in conflict with this Assignment;

AND, I HEREBY further covenant and agree that I will cooperate with Assignee, its lawful successors and assigns, or, in case that the rights in this Invention are further transferred from Assignee to an affiliate company, with the affiliate company in a manner consistent with existing and ongoing obligations under the Proprietary Rights and Confidentiality Agreement.

IN TESTIMONY WHEREOF, I have hereunto set my hand.

Assignor(s):

Name: Karsten Bruening

Signature: Karsten Bruening

Date: 19 Mar 2019

Name: Jun Amano

Signature: Jun Amano

Date: 3/20/19